



Title of Change:	Qualification of ASE Shanghai for Assembly of LQFP-32L 7X7 Devices using 1.2 mil Au Wire with Matte Tin Finish.	
Proposed first ship date:	9 October 2018 or earlier upon customer approval	
Contact information:	Contact your local ON Semiconductor Sales Office or <Min.Kwak@onsem.com>	
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com>	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Shiela.Crosby@onsemi.com>	
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
Change Part Identification:	Affected products will be identified with assembly site marking as "AS".	
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Advanced Semiconductor Engineering Shanghai
Description and Purpose:		
This notice is to announce the qualification of Advanced Semiconductor Engineering (ASE) located in Shanghai, China as a new source for assembly of LQFP 32L 7X7 devices using 1.2 mil gold wire with matte tin finish. This allows additional manufacturing capacity and manufacturing flexibility to the previous Assembly site, Amkor Philippines. BOM change to reflect standard material at ASE Shanghai. Upon completion of the qualification, assembly manufacturing of affected devices can be manufactured from either source.		
Material to be changed	Before Change Description	After Change Description
Leadframe	C194	C7025
Epoxy	3230	CRM1076



Reliability Data Summary:

The qualification is performed per type of package.

The principle of similarity will be applied: 1 qualification on 1 representative product will serve for all products qualified.

QV DEVICE NAME: 12197-512-XTD

RMS : O42901

PACKAGE : LQFP 32L, 7X7

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/320
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/320
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/320
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		0/640
SD	JSTD002	Ta = 245C, 10 sec		0/60

Electrical Characteristic Summary:

N/A

List of Affected Standard Parts:

Part Number	Qualification Vehicle
A5191HRTLГ-XTD	12197-512-XTD
A5191HRTLГ-XTP	12197-512-XTP

Please be informed that there are Customer Specific parts impacted by this Notification, thus MPN & CPN info will not be reflected in the parts list of this Generic document. Instead please click the link to the addendum PCN copy provided in the email notification to see full list of affected products specific to your company.